ASSOCIATION	N CONNECTING IN CONNECTING IN DUSTRIES® MARTIN COMP	PC, Bannockb	urn, Illinois. A	All rights reserved untions.	under both	This docume level parts, t	ent is a declara he declaration	ation c i encoi	of the substances mpasses all lowe	within the r level ma	e manufactur terials for wi	er listed i hich the n	tem. Note nanufactur	: if the item is an as rer has engineering	ssembly with lowe responsibility.
1752-21.1					Form Type Distribute	*	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					als and Mfg Information			
Supplie	r Information														
Company	name*	Company un	Company unique ID			Unique ID Authority					Response Date*				
onsemi												2023-06-08			
Contact N	lame		Title - Contact]	Phone - Contact*					Email - Contact*			
Product-l	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Authorize	ed Representative*		Title - Representative]	Phone - Representative*				Email - Representative*				
Product-l	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr Item L78LR05		Number Mfr Item Name				Effective Dat	Effective DateVersionManufacturing Site2023-06-08PHM		ring Site	Weight*		UOM	Unit Type	
			5E-MA-E	E-MA-E 24V, 5V/0.5A OUT Voltage Regulator			2023-06-08				350.0 mg		Each		
/Ianufa	cturing Proccess Informa	tion													
	Terminal Plating / Grid Array Ma	Ferminal Base Alloy J-STD-020 MS		L Rating	Peak Process Body Temperat		ure Max Time at Peak Temper		Temperat	ture Nur	nber of Reflow Cy	cles			
contains Bi			CU Alloy NA				0 C 30			seconds 3					
Comments	8														
or more	information regarding material	composition	please refer to	o page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed				
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et					
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of				
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted				
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).						
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.									
Supplier Digital Signature	astislav Drska	Le							

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

sigma range of distribution unless	otherwise noted).					-		-
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.09	mg	Supplier	Silicon (Si)	7440-21-3		2.0823	mg
			Supplier	Polyimide	Proprietary Data		0.0077	mg
Die Attach	0.61	mg	Supplier	Silver (Ag)	7440-22-4		0.0183	mg
			А	Lead (Pb)	7439-92-1	7a	0.5734	mg
			Supplier	Tin (Sn)	7440-31-5		0.0122	mg
			Supplier	Copper (Cu)	7440-50-8		0.0061	mg
Lead Frame	200.55	mg	Supplier	Tin (Sn)	7440-31-5		0.2808	mg
			Supplier	Copper (Cu)	7440-50-8		200.2692	mg
Mold Compound-Black	139.54	mg		Brominated epoxy resin	proprietary data		1.814	mg
			Supplier	Epoxy Phenol Resin	Proprietary Data		16.0471	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		2.7908	mg
			Supplier	Carbon Black (C)	1333-86-4		0.6977	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		14.9308	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		103.2596	mg
Plating	7.08	mg	В	Bismuth (Bi)	7440-69-9		0.0425	mg
			Supplier	Tin (Sn)	7440-31-5		7.0375	mg
Wire Bond - Au	0.13	mg	Supplier	Gold (Au)	7440-57-5		0.13	mg